Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.029 X .029”**

**ANODE**

**.050”**

**.050”**

**Top Material: Al**

**Backside Material: TiNiAg**

**Bond Pad Size: .029” X .029”**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .050” X .050” DATE: 11/10/21**

**MFG: SILICON SUPPLIES THICKNESS .010” P/N: 1N5806**

**DG 10.1.2**

#### Rev B, 7/1